

Attachment No. 2

Minutes of the CE-2.9 Subcommittee on Sockets 16 – 17 May 2005 New Orleans, LA

Facilitator Bill Peverill welcomed everyone, and said that the meeting would be conducted following the published agenda. It was reported that former subcommittee chair Harvey Waltersdorf would be unable to continue with the committee and has resigned.

1. The minutes of the 4 – 5 October 2004 meeting in San Diego, CA were approved.

2. REAFFIRMED DOCUMENTS

SP-4970: EIA-540DAAA-A: Detail, DIP

Carl Fritz reported that there were six approved ballots received on this standard by the ballot expiration date and no comments. It was unanimously moved and approved to send the specification to EIA for EDEC ballot.

SP-4971: EIA-700A0AB: 68-pin Memory Card Connector

Carl Fritz reported that there were six approved ballots received on this standard by the ballot expiration date and no comments. It was unanimously moved and approved to send the specification to EIA for EDEC ballot.

3. PINK SHEET BALLOTS

SP-3874: Detail, SODIMM (Tyco is sponsor. New draft needed!)

It was unanimously moved and approved to cancel the project since there is no longer any participation by Tyco.

SP-4965: Rev. EIA-540B0AE: Detail Land Grid Array (Contech Research is sponsor)

Carl Fritz reported that Contech Research would like to create a new Test Sequence standard as part of the EIA-1000 series standards and then supersede this document by the new standard. The new standard would cover both LGA and BGA sockets. The committee unanimously approved of this action to obtain a project number and proceed to letter ballot.

SP-4973: EIA-540B0AB: Low Pin Count BGA

Carl Fritz reported that Contech Research would like to create a new Test Sequence standard as part of the EIA-1000 series standards and then supersede this document by the new standard. The new standard would cover both LGA and BGA sockets. The committee unanimously approved of this action to obtain a project number and proceed to letter ballot.

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SP-4982: EIA-5400000A: Generic

It was moved and approved to send to EIA for a second short 30 day SP ballot due to insufficient votes at the last ballot for reaffirmation. Carl Fritz to contact EIA to process.

SP-4983: EIA-540BAAA-A: Detail, Mechanically Actuated PGA (Contech Research is the sponsor)

The project leader has requested that the project be cancelled. It was unanimously moved and approved to cancel the project.

4. DRAFT DOCUMENTS

SP-5055: Replacement document for EIA-676 Detail, SFF 1.8 inch (45.7 mm) Disk Drives

Carl Fritz to send the reformatted specification to EIA for SP ballot.

5. FIVE YEAR REVIEW

EIA-540C000: Sectional Relay Sockets (John Bruno of Deutsch is reviewing)

It was unanimously moved and approved that Carl Fritz send out the specification on SP ballot to reaffirm since there has been no response from Deutsch. In the event of insufficient SP ballots, the committee may take action at the next meeting to rescind the specification

EIA-540CA00: Blank, Relay Sockets (John Bruno of Deutsch is reviewing)

It was unanimously moved and approved that Carl Fritz send out the specification on SP ballot to reaffirm since there has been no response from Deutsch. In the event of insufficient SP ballots, the committee may take action at the next meeting to rescind the specification

EIA-540CAAA: Detail, 10A Relay Socket (John Bruno of Deutsch is reviewing)

It was unanimously moved and approved that Carl Fritz send out the specification on SP ballot to reaffirm since there has been no response from Deutsch. In the event of insufficient SP ballots, the committee may take action at the next meeting to rescind the specification

EIA-540CAAB: Detail, 5A Relay Socket (John Bruno of Deutsch is reviewing)

It was unanimously moved and approved that Carl Fritz send out the specification on SP ballot to reaffirm since there has been no response from Deutsch. In the event of insufficient SP ballots, the committee may take action at the next meeting to rescind the specification

It was moved and approved to send out the following documents for reaffirmation. Carl Fritz to process:

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets

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- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

SP-5058: EIA-720: Detail, SFF 2.5" Disk Drives

Carl Fritz reported that there were 2 approvals received and 2 abstentions. The committee unanimously moved and approved sending the specification to EIA for EDEC ballot.

SP-5056: EIA-674: Detail, SFF 1.8" Disk Drives

Carl Fritz reported that there were 2 approvals received, 2 abstentions and 1 approved with a typographical editorial comment. The committee unanimously moved and approved sending the specification to EIA for EDEC ballot.

SP-5059: EIA-677: Detail, SFF Power Connector Pin Dimensions

It was reported at the October 2005 meeting that the ballot was issued on 3 June 2004. The committee unanimously moved and approved sending the specification to EIA for EDEC ballot if there were no negative comments received.

6. NEW BUSINESS

There was no new business to report.

All actions taken by the subcommittee were unanimously moved and approved by the EIA CE-2.0 committee. The meeting adjourned at 9:40 AM on 17 May 2005.

Respectfully,

Carl Fritz, Recording Secretary

Bill Peverill, Facilitator CE-2.9